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AF/ 1765  
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THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: David Mui et al.

Appln No.: 09/905,172

Filed: July 13, 2001

Title: ETCH PATTERN DEFINITION USING A CVD ORGANIC LAYER AS  
AN ANTI-REFLECTION COATING AND HARDMASK

Art Unit: 1765

Examiner: Deo, Duy Vu Nguy

Docket No.: 004227 USA02/ETCH/SILICON/JB1

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Record

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Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

**APPEAL BRIEF UNDER 37 C.F.R. §1.192**

Sir:

As set forth in the Notice of Appeal filed by first-class mail on October 13, 2004, Appellants hereby appeals the final decision of the Examiner in the above-identified application rejecting claims 8-11 and 13-40, which are all of the pending claims in the application. Appellant respectfully requests that the Board of Patent Appeals and Interferences reverse the Examiner's rejection of the claimed subject matter.

This Appeal Brief is filed in triplicate as required.

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